

AMD-Based Platforms

- Cloud Platforms
- HPC / GPU Platforms
- Embedded & SMB Platforms



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To be the leader in providing servers, technical workstations and supercomputer clusters through worldwide channels.



◆ About TYAN

Created in 1989, TYAN designs, manufactures and markets advanced x86 server/workstation platforms. TYAN's products are sold to OEMs, VARs, System Integrators, and Resellers around the world for a wide range of applications. As a leading server brand asset owned by MiTAC International Corporation, TYAN is to be deeply enhanced and further developed through the synergy and innovation of the new MiTAC.

Products from TYAN feature design enhancements specifically developed for enterprise computer room and data center environments. These highly stable, space-efficient products are very attractive to OEMs and System Integrators designing next generation rackmount server solutions for a wide array of applications.

With design and engineering centers located in the U.S., China, and Taiwan, TYAN holds a distinct advantage over the competition. TYAN's engineers are well-positioned to assist customers with the development of tailored solutions that meet their requirements. Customers are assured that TYAN products meet the highest quality and reliability standards available.

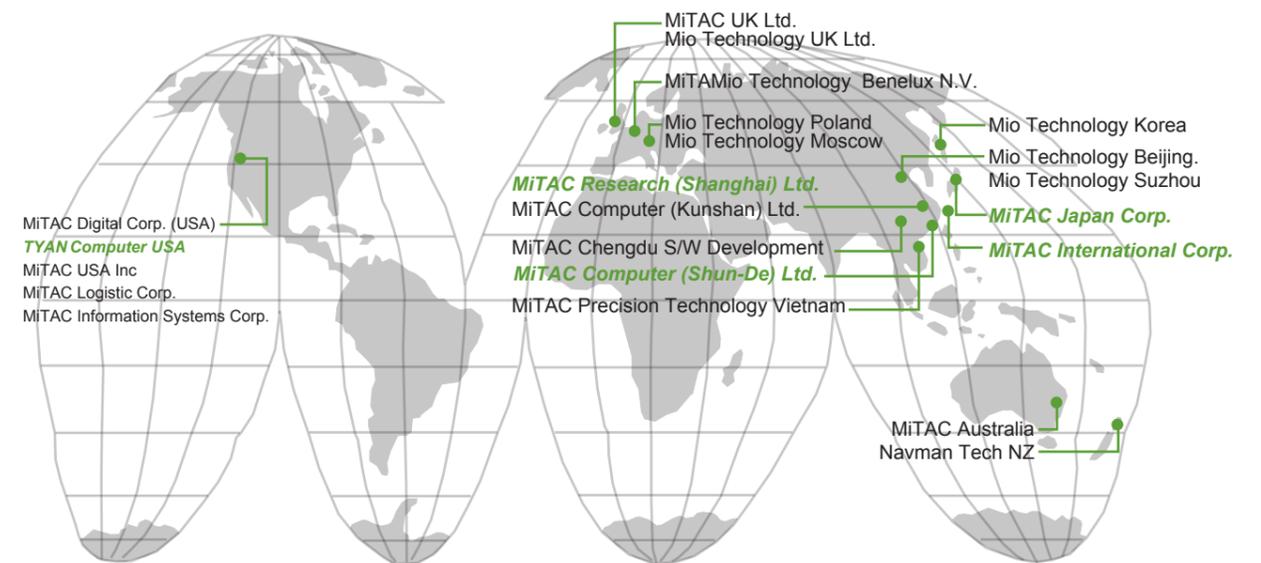
TYAN enables its customers to be technology leaders by providing scalable, highly-integrated, reliable platforms for a wide range of applications such as high-end server and workstation usage in markets such as CAD, DCC, E&P and HPC. TYAN's time-to-market strategies and cutting-edge engineering processes distinguish them from the competition. Many TYAN customers have had their TYAN-based products recognized within their industries, garnering a multitude of distinguished awards.

◆ Recent Wins on the TOP 500

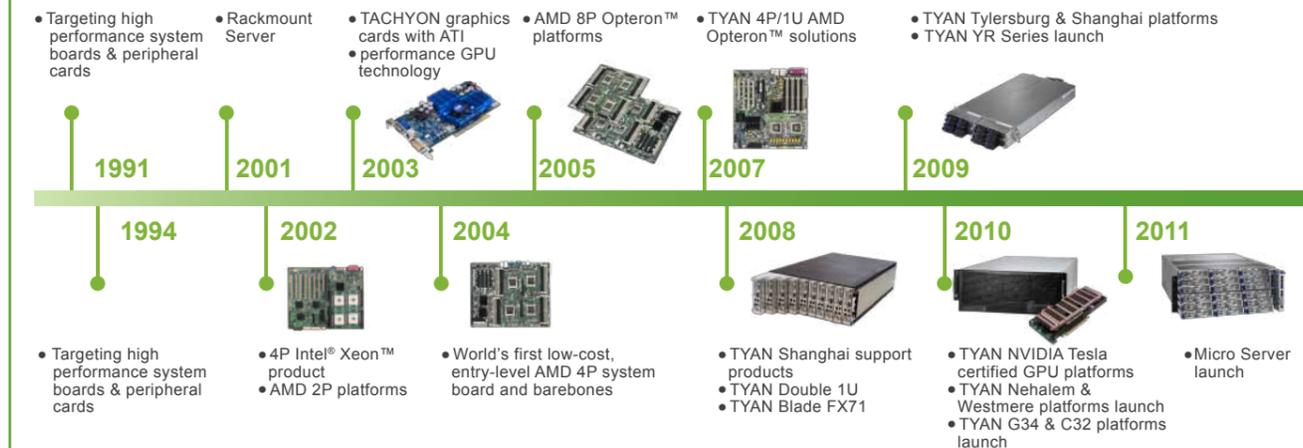


Jun. 2010	#19 of Top 500	8.5 Mole, IPE, CAS, China
Nov. 2008	#10 of Top 500	Dawning 5000A, Dawning, China
Jun. 2008	#16 of Top 500	T2K Open Supercomputer, Hitachi, Japan
Jun. 2006	#34 of Top 500	PACS-CS, Hitachi-Fujitsu, Japan
Jun. 2004	#10 of Top 500	Dawning 4000A, Dawning, China

◆ MiTAC Global Presence & TYAN Branch Offices



◆ TYAN Milestone



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AMD-BASED CLOUD PLATFORMS

The majority of cloud computing infrastructure consists of reliable services delivered through data centers and built on lots of servers. Data centers have to install, operate, and manage huge number of servers so the topics of server density, power-efficiency, and serviceability are heavily emphasized. TYAN provides a full array of cloud platforms offering scalability, reliability, remote management ability and high performance that is designed for Cloud Computing environments.



Micro Serve Computing Node



Lower Power & Higher Density Cloud Platforms Micro Server

The TYAN Micro Server provides high-reliability and scalable performance with 18 removable front-loaded compute nodes, and redundant (2+1) hot-swap power supplies. Each individual node supports a AMD Athlon II X4 / X2 Processors, up to 32 GB of un-buffered ECC DDR3 memory, and two 2.5" SSD or HDD drives. Each node has 1 G-bit network port and features IPMI 2.0 support for out-of-band and remote management.

Yellow River Computing Node

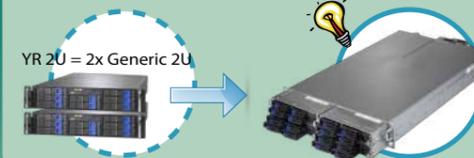


Higher Density Cloud Platforms TYAN Yellow River Series

The TYAN Yellow River Series is an ultra high density twin server platform that featured with scalable, modular, space effective, manageable, efficient, flexibility and fast through put.

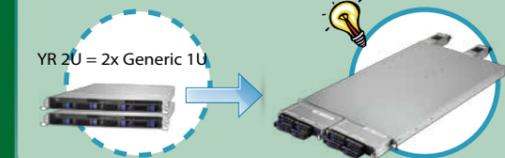
Blade Servers in 2U!!

- The Traditional Way** Expand-on-the-top
2x Computing Power, BUT
2x space, 2x rail kit
- The New Way** Expand-on-the-side
2x Computing Power
No height growth, Blade Serviceability



Blade Servers in 1U!!

- The Traditional Way** Expand-on-the-top
2x Computing Power, BUT
2x space, 2x rail kit
- The New Way** Expand-on-the-side
2x Computing Power
No height growth, Blade Serviceability



Cloud Platform — Lower Power & Higher Density

FM65-B8001

B8001F65X18-160V2R

Cloud Platform
Lower Power & Higher Density



Most Cost-Effective, High-Density Server Platform for IPDC

- 4U with eighteen (18) front swappable blades
- Up to 32GB main memory supported in single-socket server platform
- (2+1) hot-swappable redundant, 80-PLUS Platinum rated RPSU for all blades



Model Number	FM65-B8001		
Enclosure Form Factor	4U (27.5" in depth) / 18 Nodes		
Supported CPU (per node)	(1) AMD 45nm Quad-Core Opteron™ 1300 Series Processors (Budapest / Suzuka)		
Chipset (per node)	AMD SR5650 + SP5100		
Number of DIMM Slot (per node)	4		
Memory Type (max. capacity) (per node)	U-DDR3 1333/1066 w/ ECC (32GB)		
Storage Controller	2-port SATA-II		
Networking (per node)	Max. (2) GbE		
RAID Support	RAID 0/1/10		
Multimedia Drive	N/A		
Standard Model	B8001F65X18-160V2R	Storage Backplane	Power Supply
	(2) fixed 2.5" SATA-II	N/A	1600W (2+1) RPSU

Cloud Platform — Higher Density

YR190-B8028-X2

B8028Y190X2-030V4H

Cloud Platform
Higher Density



Model Number	YR190-B8028		
Enclosure Form Factor	1U (28.74" in depth) / 2 Nodes		
Supported CPU	(1) AMD Opteron™ 6100 Series (Magny-Cours) AMD Opteron™ Next-Gen processors		
Chipset	AMD SR5650 + SP5100		
Chipset Interconnection	HyperTransport™ Link 3.0		
Number of DIMM Slot	12		
Memory Type (max. capacity)	R-DDR3 1333/1066/800 w/ ECC (192GB)	U-DDR3 1333/1066 w/ ECC (96GB)	
Storage Controller	AMD SP5100 4-port SATA-II		
RAID Support	RAID 0, 1, 10, 5 (Promise RAID Stack)		
Multimedia Drive	N/A		
Networking	(2) GbE + (1) BMC Port		
PCI Expansion Slots	(1) PCIe Gen.2 x16		
Standard Model	B8028Y190X2-030V4H	Storage Backplane	Power Supply
	(4) Hot-swap SATA-II (per node)	(1) 4-port SAS/ SATA-II (per node)	(1) ERP1U 300W (per node)

Cloud Platform — Higher Density

YR190-B8228-X2

B8228Y190X2-045V4H

Cloud Platform
Higher Density



Model Number	YR190-B8228		
Enclosure Form Factor	1U (28.74" in depth) / 2 Nodes		
Supported CPU	(2) AMD Opteron™ 4100 Series (Lisbon)		
Chipset	AMD SR5650 + SP5100		
Chipset Interconnection	HyperTransport™ Link 3.0		
Number of DIMM Slot	12/ (6+6)		
Memory Type (max. capacity)	R-DDR3 1333/1066/800 w/ ECC (192GB)	U-DDR3 1333/1066 w/ ECC (32GB)	
Storage Controller	AMD SP5100 4-port SATA-II		
RAID Support	RAID 0, 1, 10, 5 (Promise RAID Stack)		
Multimedia Drive	N/A		
Networking	(3) GbE		
PCI Expansion Slots	(1) PCI-E Gen.2 x16		
Standard Model	B8228Y190X2-045V4H	Storage Backplane	Power Supply
	(4) Hot-swap SATA-II (per node)	(1) 4-port SAS/ SATA (per node)	(1) ERP1U 450W (per node)



AMD-BASED HPC / GPU PLATFORMS



The TYAN HPC / GPU Intensive Server Platforms are designed for the high performance computing and massive parallel computing environments. These solutions provide superior parallel computing capability and are designed to deliver scalability, reliability and the best price/performance to support complicated computational applications.

Target Applications

- Bio-informatics and Life Sciences,
- Computational Chemistry, Computational Electromagnetics and Electrodynamics
- Computational Finance and Computational Fluid Dynamics
- Data Mining, Analytics and Databases
- Computer Vision, MATLAB Acceleration and Medical Imaging, Molecular Dynamics, Weather and Atmospheric
- Ocean Modeling and Space Sciences

Unique GPU Platform Benefits

- Support AMD Opteron™ 4100/6100 Series Processors (Lisbon / Magny-Cours)
- Support GPU computing processors
- Over 2 Teraflops of Double Precision Performance
- Up to 3,584 for massively parallel computing performance
- Unique GPU platform design with increased energy efficiency
- Optimized design reduces rack space requirements
- Cost Effective – Up to 8 GPU computing processors in a 4U system

FT48-B8812

B8812F48W8HR



Model Number	FT48-B8812
Enclosure Form Factor	4U (27.5" in depth)
Supported CPU	(4) AMD Opteron™ 6100 Series (Magny-Cours) AMD Opteron™ Next-Gen processors
Chipset	AMD SR5690 + SP5100
Chipset Interconnection	HyperTransport™ Link 3.0
Number of DIMM Slot	32/ (8+8+8+8)
Memory Type (max. capacity)	R-DDR3 1333/1066/800 w/ ECC (256GB) U-DDR3 1333/1066 w/ ECC (128GB)
Storage Controller	LSI SAS2008 SAS 6G
RAID Support	RAID 0, 1, 1E, 10
Multimedia Drive	N/A
Networking	(3) GbE
PCI Expansion Slots	(1) FH/FL PCI-E Gen.2 x16 slot (w/ x16 or x8 link) (1) FH/FL PCI-E Gen.2 x8 slot (w/ x0 or x8 link) (2) FH/FL PCI-E Gen.2 x8 slots

Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B8812F48W8HR	(8) Hot-Swap SAS/SATA-II	(2) 4-port SAS/ SATA	1540W (2+1) RPSU

GN70-B8236-HE

B8236G70W8HR-HE



Model Number	GN70-B8236-HE
Enclosure Form Factor	2U (27.56" in depth)
Supported CPU	(2) AMD Opteron™ 6100 Series (Magny-Cours) AMD Opteron™ Next-Gen processors
Chipset	AMD SR5690 + SR5650 + SP5100
Chipset Interconnection	HyperTransport™ Link 3.0
Number of DIMM Slot	16/ (8+8)
Memory Type (max. capacity)	R-DDR3 1333/1066/800 w/ ECC (256GB) U-DDR3 1333/1066 w/ ECC (64GB)
Storage Controller	LSI SAS2008 SAS 6G
RAID Support	RAID 0, 1, 1E, 10
Multimedia Drive	(opt.) Slim DVD-ROM
Networking	(3) GbE
PCI Expansion Slots	(2) FH/FL PCI-E Gen.2 x16 slots (for 2x GPU installation) (2) FH/FL PCI-E Gen.2 x8 slots

Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B8236G70W8HR-HE	(8) Hot-swap SAS	8-port SAS/ SATA	770W (1+1) RPSU

YR292-B8239-X4

B8239Y292X4-080V4HRI-IL



Cloud Platform
Higher Density



Model Number	YR292-B8239-IL
Enclosure Form Factor	2U (28.74" in depth) / 4 nodes
Supported CPU	(2) AMD Opteron™ 6100 Series (Magny-Cours) AMD Opteron™ Next-Gen processors
Chipset (per node)	AMD SR5670+SP5100
Chipset (per node)	AMD SR5670+SP5100
Chipset Interconnection	HyperTransport Link 3.0 (up to 6.4GT/s per link)
Number of DIMM Slot (per node)	(4) + (4)
Memory Type (max. capacity)(per node)	R-DDR3 1600/1333/1066/800 w/ECC (128GB) U-DDR3 1600/1333/1066 w/ ECC (128GB)
InfiniBand (per node)	(1) QSFP port/ Mellanox ConnectX-2 MT25418B0-FCCR-QIS
Storage Controller	AMD SP5100 4-port SATA-II
RAID Support (per node)	RAID 0, 1, 10, 5 (Promise RAID stack)
Multimedia Drive (per node)	N/A
PCI Expansion Slots (per node)	(1) PCI-E Gen. 2 x 16

Standard Model	Number of HDD in Each Node	Storage Backplane	Power Supply
B8239Y292X4-080V4HRI-IL	(4) Hot-swap SATA-II (per node)	(1) 4-port SAS/ SATA-II (per node)	800W (1+1) RPSU

AMD Opteron™ 6100 Series Processor



S8812

S8812WGM3NR

Processor	• Quad G34 sockets support AMD Opteron™ 6100 series processors (Magny-Cours) • AMD Opteron™ Next-Gen processors
Chipset	• AMD SR5690 + SP5100
Memory	• (8+8+8+8) DDR-III DIMM slots • Support up to 512GB of R-DDR3 1333/1066/800 w/ ECC memory • Support up to 128GB of U-DDR3 1333/1066 w/ ECC memory
Expansion	• (1) PCI-E Gen.2 x16 slot (w/ x16 or x8 link) • (1) PCI-E Gen.2 x8 slot (w/ x0 or x8 link) • (2) PCI-E Gen.2 x8 slots
Storage	• (1) SATA-II 3.0 Gb/s • (8) SAS 6G ports w/ RAID 0, 1, 1E, 10 support (LSI SAS2008)
Network	• (3) GbE (via Intel® dual-port 82576EB and Intel® 82574L)
Video	• ASPEED AST2050 Integrated graphics
Management	• ASPEED AST2050 (IPMI v2.0 compliant w/ iKVM)
Form Factor	• MEB (16.2" x 13", 411.48mm x 330mm)

AMD Opteron™ 6100 Series Processor



S8232

S8232WGM4NR / S8232WAG2NRF-LE

Processor	• Dual G34 sockets support AMD Opteron™ 6100 series processors (Magny-Cours) • AMD Opteron™ Next-Gen processors
Chipset	• AMD (2) SR5690 + SP5100
Memory	• (12+12) DDR-III DIMM slots • Support up to 256GB of R-DDR3 1333/1066/800 w/ ECC memory • Support up to 64GB of U-DDR3 1333/1066 w/ ECC memory
Expansion	• (4) PCI-E Gen.2 x16 slots • (2) PCI-E Gen.2 x 8 slots (w/ x4 link) • (1) PCI 32/33MHz slot
Storage	• (6) SATA-II connectors running at 3.0 Gb/s w/ RAID 0, 1, 10, 5 support • (8) SAS 6G ports w/ RAID 0, 1, 1E, 10 support (LSI SAS2008)
Network	• (4) GbE (via two Intel® dual-port NIC 82576EB)
Video	• ASPEED AST2050 Integrated graphics
Audio	• Realtek ALC262 audio CODEC
Firewire	• VIA VT6308P 1394a controller
Management	• ASPEED AST2050 (IPMI v2.0 compliant w/ iKVM)
Form Factor	• MEB (16.2" x 13", 411.48mm x 330mm)

* For SATA Version or workstation Version, Please Visit TYAN Website for more information.

AMD Opteron™ 6100 Series Processor



S8239-IL

S8239GM2NRI-IL (BTO)

Processor	• Dual G34 sockets support AMD Opteron™ 6100 HE series processors (Magny-Cours) • AMD Opteron™ Next-Gen processors
Chipset	• AMD SR5670+SP5100
Memory	• (4+4) DDR3 DIMM slots • Support up to 128GB of Registered DDR-3 1333/1066/800 w/ ECC Memory
Memory Type (max. capacity)	• R-DDR3 1600/1333/1066/800 w/ECC (128GB) • U-DDR3 1600/1333/1066 w/ ECC (128GB)
Expansion	• (1) PCI-E Gen. 2 x 16
Storage	• (4) SATA-II ports running at 3.0 Gb/s w/ RAID 0, 1, 10, 5 support
Network	• (2) GbE (via 2x Intel 82574)(1) QSFP port/ Mellanox ConnectX-2 MT25418B0-FCCR-QIS
Video	• ASPEED AST 2050 Integrated graphics
Management	• ASPEED AST 2050 (IPMI v2.0 compliant w/ iKVM)
Form Factor	• TYAN SFF (6.3" x 18", 160mm x 457.2mm)



AMD-BASED SMB PLATFORMS

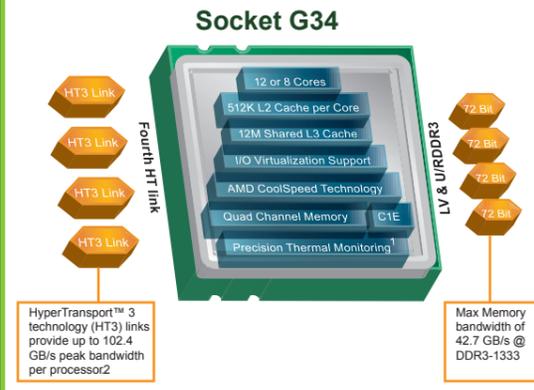
TYAN provides various platforms that built for SMB (Small and Medium Business) environments. Featuring with affordable, simple set-up, easy management and fitting in industry standard operation systems, TYAN products are the ideal platforms for small and remote office, entry-level server, and rack mount server room.



The AMD Opteron™ 6100 Series Processor

The AMD Opteron™ 6100 Series platform, offering the industry's only twelve-core x86 processor. Built to excel when the workload gets tough.

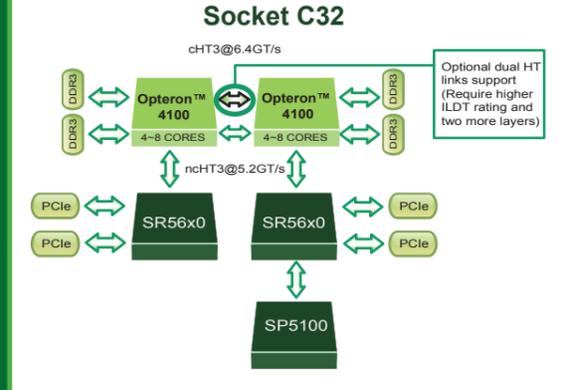
AMD Opteron™ 6100 Series Processor



The AMD Opteron™ 4100 Series Processor

The AMD Socket C32 is the server processor socket for AMD's single-CPU and dual-CPU Opteron™ 4100 series CPUs.

AMD Opteron™ 4100 Series Processor



1U Server

GT24-B8236-IL

B8236G24W4H-IL / B8236G24V4H-IL



Model Number	GT24-B8236-IL
Enclosure Form Factor	1U (25.4" in depth)
Supported CPU	(2) AMD Opteron™ 6100 Series (Magny-Cours) AMD Opteron™ Next-Gen processors
Chipset	AMD SR5690 + SP5100
Chipset Interconnection	HyperTransport™ Link 3.0 (up to 6.4GT/s per link)
Number of DIMM Slot	16 (8+8)
Memory Type (max. capacity)	Registered, DDR-3 1600/1333/1066/800 w/ ECC (128GB)
Storage Controller	LSI SAS2008 8-port SAS 6G (B8236G24W4H) AMD SP5100 6-port SATA-II (B8236G24V4H)
RAID Support	0, 1, 10, 1E (SAS 6G) 0, 1, 10, 5 (SATA-II)
Multimedia Drive	(Opt.) Slim DVD-ROM, 8x
Networking	(3) GbE
PCI Expansion Slots	(2) FH/HL PCI-E Gen.2 x16 slots

Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B8236G24V4H-IL	(4) Hot-swap SATA-II	4-port SAS/ SATA	500W PSU
B8236G24W4H-IL	(4) Hot-swap SAS 6G	4-port SAS/ SATA	500W PSU

AMD Opteron™ 6100 Series Processor



S8236-IL

S8236GM3NR-IL / S8236WGM3NR-IL / S8236WGM3NR-HE-IL (BTO)

Processor	• Dual G34 sockets support AMD Opteron™ 6100 series processors (Magny-Cours) • AMD Opteron™ Next-Gen processors
Chipset	• AMD SR5690 + SP5100 • AMD SR5690 + SR5650 + SP5100 (S8236WGM3NR-HE-IL)
Memory	• (8+8) DDR-3 DIMM slots • Support up to 128GB of Registered DDR-3 1600/1333/1066/800 w/ ECC memory
Expansion	• (2) PCI-E Gen.2 x16 slots (S8236GM3NR/S8236WGM3NR-IL) • (3) PCI-E Gen.2 x16 slots (S8236WGM3NR-HE-IL)
Storage	• (6) SATA-II ports by (1) mini-SAS connector and (2) SATA connectors running at 3.0 Gb/s w/ RAID 0, 1, 10, 5 support • (8) SAS 6G ports by (2) mini-SAS connectors w/ RAID 0, 1, 10, 1E support (S8236WGM3NR/S8236WGM3NR-HE-IL)
Network	• (3) GbE (via Intel® dual-port 82576EB and Intel® 82574L)
Video	• ASPEED AST2050 integrated graphics
Management	• ASPEED AST2050 (IPMI v2.0 compliant w/ iKVM)
Form Factor	• Extended ATX (12" x 13", 305mm x 330mm)

1U Server

GT24-B8226

B8226G24V4H / B8226G24W4H



Model Number	GT24-B8226
Enclosure Form Factor	1U (25.4" in depth)
Supported CPU	(2) AMD Opteron™ 4100 Series (Lisbon)
Chipset	AMD SR5690 + SP5100
Chipset Interconnection	HyperTransport™ Link 3.0 (up to 6.4GT/s per link)
Number of DIMM Slot	12 (6+6)
Memory Type (max. capacity)	Registered, DDR-3 1333/1066/800 w/ ECC (96GB)
Storage Controller	LSI SAS2008 8-port SAS 6G (B8226G24W4H) AMD SP5100 6-port SATA-II (B8226G24V4H)
RAID Support	0, 1, 10, 1E (SAS 6G) 0, 1, 10, 5 (SATA-II)
Multimedia Drive	(Opt.) Slim DVD-ROM, 8x
Networking	(3) GbE
PCI Expansion Slots	(2) FH/HL PCI-E Gen.2 x16 slots

Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B8226G24V4H	(4) Hot-swap SATA-II	4-port SAS/ SATA	500W PSU
B8226G24W4H	(4) Hot-swap SAS 6G	4-port SAS/ SATA	500W PSU

AMD Opteron™ 4100 Series Processor



S8225

S8225WAGM4NRF / S8225AGM4NRF

Processor	• Dual C32 sockets support AMD Opteron™ 4100 series processors (Lisbon)
Chipset	• AMD (2) SR5690 + SP5100
Memory	• (4+4) DDR-III DIMM slots • Support up to 128GB of R-DDR3 1333/1066/800 w/ ECC memory • Support up to 32GB of U-DDR3 1333/1066 w/ ECC memory
Expansion	• (4) PCI-E Gen.2 x16 slots • (1) PCI-E Gen.2 x8 slot (x4 link) • (1) PCI-E Gen.2 x4 slot • (1) PCI 32/33MHz slot
Storage	• (6) SATA-II connectors running at 3.0 Gb/s w/ RAID 0, 1, 10, 5 support • (8) SAS 6G ports w/ RAID 0, 1, 1E, 10 support (LSI SAS2008)
Network	• (4) GbE (via Intel® dual-port NIC 82576EB and two Intel® 82574L)
Video	• ASPEED AST2050 integrated graphics
Audio	• Realtek ALC262 audio CODEC
Firewire	• VIA VT6308P 1394a controller
Management	• ASPEED AST2050 (IPMI v2.0 compliant w/ iKVM)
Form Factor	• EATX (12" x 13", 305mm x 330mm)



AMD-BASED EMBEDDED PLATFORMS

The ideal platforms for telecom, networking, storage, medical imaging, embedded servers, security and surveillance appliances.



The Benefits of TYAN's AMD Based Embedded Platforms

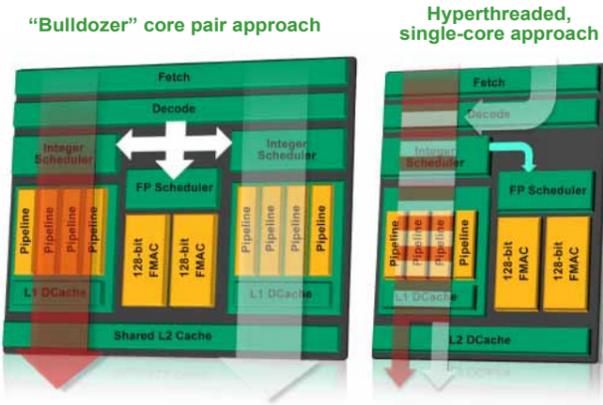
- Adopting the latest AMD technology
- Available with customized features, BOM enhancement or modified designs
- Platforms designed to meet high reliability, safety and environmental requirements
- Lower-power consumption options available
- Designed for continuous operation (7x24x365)
- Designed for longer operational life cycle (7+ years)
- Platforms and CPU longevity aligned for embedded use
- JTAG header option available for use with SAGE Engineering's integrated software development and debug tool



Today's TYAN G34 and C32 platforms are ready for "Bulldozer" technology!

- No platform transitions are required for the first "Bulldozer" products
- "Bulldozer" dynamically switches between shared and dedicated components to maximize performance per watt
- New "Bulldozer" instructions including SSSE3, SSE 4.1, SSE 4.2, AES, XSAVE, AVX, FMAC, XOP and more
- "Bulldozer" adds Flex FP: the world's ONLY flexible 256-bit FPU
- "Bulldozer" has Turbo CORE: The industry's BEST full-core boost
- "Bulldozer" technology provides up to 50% memory throughput increase compared to current products with LR-DIMM and LV-DDR3 support and new memory management features
- "Bulldozer" results in unprecedented performance gains: up to 50% more throughput in the same power and thermal envelope as today's 12-core AMD Opteron™ processors

AMD's New Bulldozer Core Delivering Better Scalability for Multithreading



Embedded AMD Athlon™ II XLT Processors Embedded AMD Phenom™ II XLT Processors



S8005

S8005WAGM2NR / S8005AGM2NR / S8005GM2NR-LE

Processor	• Single AM3 socket support AMD Athlon™ II XLT & AMD Phenom™ II XLT processors
Chipset	• AMD SR5670 + SP5100 (S8005WAGM2NR/ S8005AGM2NR) • AMD SR5650 + SP5100 (S8005GM2NR-LE)
Memory	• (4) DDR-III DIMM slots • Support up to 16GB of Un-buffered DDR-3 1333/1066 • (1) PCI-E Gen.2 x16 slot
Expansion	• (1) PCI-E Gen.2 x8 slot (S8005WAGM2NR/ S8005AGM2NR) • (2) PCI 32/33MHz slots
Storage	• (4) SAS connectors running at 3.0 Gb/s w/ RAID 0, 1, 10 support (S8005WAGM2NR) • (6) SATA-II connectors running at 3.0 Gb/s w/ RAID 0, 1, 10 support
Network	• (2) GbE (via 2x Intel® 82574L)
Audio	• Realtek ALC262 audio CODEC (S8005WAGM2NR/ S8005AGM2NR)
TPM	• Infineon SLB9635 (TPM v1.2)
Video	• ASPEED AST2050 Integrated graphics
Management	• ASPEED AST2050 (IPMI v2.0 compliant w/ iKVM)
Form Factor	• ATX (12" x 9.6", 305mm x 243.8mm)

Ready for "Bulldozer"

Embedded AMD Opteron™ 4100 Series Processors



S8010

S8010GM2NR / S8010WGM2NR / S8010G2NR-LE

Processor	• Single C32 socket support AMD Opteron™ 4100 series processors (Lisbon)
Chipset	• AMD SR5670 + SP5100 • AMD SR5650 + SP5100(-LE SKU)
Memory	• (6) DDR-III DIMM slots • Support up to 48GB of R-DDR3 1333/1066/800 w/ ECC memory • Support up to 16GB of U-DDR3 1333/1066 w/ ECC memory
Expansion	• (1) PCI-E Gen.2 x16 slot (x8 link) • (2) PCI-E Gen.2 x8 slot (x8 link)(-LE SKU w/o one slot) • (1) PCI 32/33MHz slot
Storage	• (6) SATA-II 3.0 Gb/s w/ RAID 0, 1, 10, 5 support • (8) SAS 6G ports w/ RAID 0, 1, 1E, 10 support (LSI SAS2008)
Network	• (2) GbE (via Intel® Intel® 82574L) • (1) BMC Port (via Broadcom BCM5221)
Video	• ASPEED AST2050 Integrated graphics
Management	• ASPEED AST2050 (IPMI v2.0 compliant w/ iKVM)
Form Factor	• ATX (12" x 9.6", 305mm x 244mm)

Ready for "Bulldozer"